ABSTRACT

WIRE SWEEP RESISTANT SEMICONDUCTOR PACKAGE AND MANUFACTURING METHOD THEREOF

A method for manufacturing a wire sweep resistant semiconductor package provides a die attached to an interposer. The die is electrically connected to the interposer with conductive wires. A sealant is applied to the conductive wires and optionally the die to prevent wire sweep, the sealant being applied free of contact with the interposer. The die, the interposer, the conductive wires, and the sealant are enclosed in an encapsulant. (Fig. 4)